



102112053

To the Honorable Commissioner of Patents

Please Record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Frank L. Hall and Todd O. Bolken

05/24/02

Additional name of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: MICRON TECHNOLOGY, INC.

Internal Address:

JCS973 U.S. PTO
10/15/02
06/24/02

Street Address: 8000 South Federal Way

City: Boise State: ID Zip: 83707

Additional Name(s) & address(es) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: May 16, 2002

4. Application number(s) or patent number(s):

10/154640

If this document is being filed together with a new application, the execution date of the application is: May 16, 2002

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning this document should be mailed:

Name: TraskBritt

Internal Address:

Street Address: P.O. Box 2550

City: Salt Lake City State: UT Zip: 84110

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

20-1469

(Attach duplicate copy of this page if paying by deposit account)

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06/04/2002 00000211 10154640
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9. Statement and signature.

Attorney Docket No.: 2269-5271US (02-0020)

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Joseph A. Walkowski
Name of Person Signing
Reg. No. 28,765

Signature

May 24, 2002
Date

Total number of pages including cover sheet, attachments, and documents:

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, each undersigned ASSIGNOR does hereby:

SELL, ASSIGN AND TRANSFER to MICRON TECHNOLOGY, INC. ("ASSIGNEE"), a corporation of the state of Delaware having a place of business at 8000 South Federal Way, Boise, Idaho 83707-0006, the entire right, title and interest for the United States and all foreign countries in and to any and all improvements which are disclosed in the Application for United States Letters Patent, which has been executed by each undersigned ASSIGNOR concurrently herewith and is entitled **APPARATUS AND METHOD FOR MOLDING A SEMICONDUCTOR DIE PACKAGE WITH ENHANCED THERMAL CONDUCTIVITY**, such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent or the legal equivalent thereof which have been or may be filed in the United States and all foreign countries relating to any of such improvements; all original, reexamined and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application made in the United States;

AUTHORIZE the ASSIGNEE to apply for and receive any and all United States and foreign patents relating to such improvements in its own name;

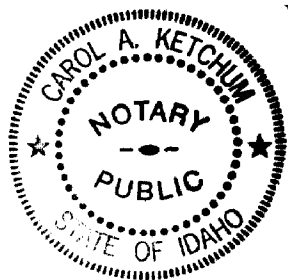
AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to and in the name of the ASSIGNEE;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement or encumbrance affecting the rights and property herein conveyed has been or will be made or entered into by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT, when requested and at the expense of the ASSIGNEE, to carry out in good faith the intent and purpose of this assignment, to execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications relating to any and all such improvements; to execute all rightful oaths, declarations, assignments, powers of attorney and other papers; to communicate to the ASSIGNEE all facts and provide to the ASSIGNEE all documents and things known and accessible to the undersigned relating to such improvements and the history thereof, and testify as to the same in any interference, litigation or other proceeding relating thereto; and generally to do everything possible which the ASSIGNEE shall consider desirable

STATE OF IDAHO)
 : ss.
COUNTY OF ADA)

BEFORE ME, the undersigned authority, on this 16th day of May, 2002, personally appeared Todd O. Bolken, personally known or proven by satisfactory documentary evidence to me to be the person whose name is subscribed to the foregoing instrument and acknowledged to me that he executed the same of his own free will for the purposes and consideration therein expressed.



Carol A. Ketchum

Notary or Consular Officer

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AUTHORIZE the ASSIGNEE to apply for and receive any and all United States and foreign patents relating to such improvements in its own name;

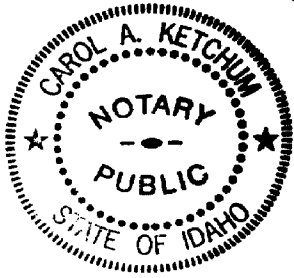
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